**Objective**

Increase the thermal conductivity of printed circuit board materials (PCBs) without loss of key material property benchmarks (i.e. mechanical strength, CTE)

**Impact**

Improve passive thermal management in electronic devices allowing for heat dissipation from electrically insulating materials and components

**Approach**

- Synthesis of Janus boron nitride (JBN) particles proposed as a novel filler material
- Directed assembly of particles during processing to achieve percolated microstructure

**Selected Publications**